Heraeus

Technical Data Sheet



THICK FILM MATERIALS

Product Type: End Terminations

Product Name: ET1893



Pb and Cd Free Plateable Silver End Termination

Description

ET1893 is a Pb and Cd free, low temperature plateable Ag End Termination. ET1893 has excellent adhesion to a variety of ceramic compositions when fired at $\leq 600^{\circ}\text{C}$. ET1893 is supplied with a rheology suitable for automatic dipping machines.

Key Benefits

- Nickel plateable
- Firing temperature less than 600 °C
- Machine dippable
- REACH¹ and ROHS² compliant

Typical Properties

Metal Type

Silver

Viscosity

15 – 30 Kcps Brookfield RVT SC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C

Solids

79.0 ± 1.0 %

FOG

Less than 10 µm (at 4th scratch)

Recommended Processing Guidelines

Drying

150 °C for 10 minutes

Firing

525 – 600 °C peak temperature Dwell time of 1 – 2 minutes at peak

Thinner:

RV-372

Warranty:

Material guaranteed to meet specifications for 6 months from date of shipment.

Storage:

Store in a dry location at 5 - 25 °C.

DO NOT REFRIGERATE.

Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

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